This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (previously presented): An epoxy resin composition for a printed wiring board, comprising:

an epoxy resin, a phenol novolac resin and a curing accelerator,

said epoxy resin comprises an epoxy (a) and an epoxy (b),

wherein the epoxy (a) is a brominated epoxy resin, obtainable by reacting/mixing a bisphenol A epoxy resin with tetrabromobisphenol A, said brominated epoxy resin having an epoxy equivalent of 350 g/eq to 470 g/eq and containing an n=0 component in a ratio of 20% to 35% in terms of area percentage in a GPC chart; and

the epoxy (b) is one or more of bifunctional epoxy resins, obtainable by reacting epichlorohydrin with any one selected from the group consisting of bisphenol A, bisphenol F and tetrabromobisphenol A, said bifunctional epoxy resins having an n=0 component in a content of 60% or higher in terms of area percentage in a GPC chart;

said epoxy (a) and epoxy (b) are contained in total in an amount of 80% to 100% by weight, based on the total weight of the epoxy resin composition;

said epoxy (a) is contained in an amount of 75% to 97% by weight, based on the total weight of the epoxy resin; and

said epoxy resin has a bromine content of 18% to 30% by weight, based on the total weight of the epoxy resin.

2. (original): An epoxy resin composition for a printed wiring board according to claim 1, characterized in that the phenol novolac resin is a phenol novolac resin, obtainable by reacting formaldehyde with one selected from the group consisting of phenol, cresol and bisphenol A; said phenol novolac resin containing a bifunctional component in an amount of 15% to 30%.

3. (previously presented): An epoxy resin composition for a printed wiring board according to claim 1, characterized in that an inorganic filler is contained.

4. (original): An epoxy resin composition for a printed wiring board described in claim 3, characterized in that a glass powder and/or silica filler is contained.

5. (previously presented): A prepreg for a printed wiring board, characterized in that the prepreg is obtainable by impregnating a glass cloth with a varnish comprising an organic solvent and an epoxy resin composition for a printed wiring board according to claim 1 and drying the vanish to B-stage.

6. (original): A laminated board for a printed wiring board, a printed wiring board or a laminated printed wiring board, characterized in that a prepreg for a printed wiring board according to claim 5 is used for the preparation thereof.

7. (previously presented): An epoxy resin composition for a printed wiring board according to claim 2, characterized in that an inorganic filler is contained.

8. (previously presented): A prepreg for a printed wiring board, characterized in that the prepreg is obtainable by impregnating a glass cloth with a varnish comprising an organic solvent and an epoxy resin composition for a printed wiring board according to claim 2 and drying the vanish to B-stage.

9. (previously presented): A prepreg for a printed wiring board, characterized in that the prepreg is obtainable by impregnating a glass cloth with a varnish comprising an organic solvent and an epoxy resin composition for a printed wiring board according to claim 3 and drying the vanish to B-stage.

10. (previously presented): A prepreg for a printed wiring board, characterized in that the prepreg is obtainable by impregnating a glass cloth with a varnish comprising an

organic solvent and an epoxy resin composition for a printed wiring board according to claim 4 and drying the vanish to B-stage.

11. (previously presented): The prepreg for a printed wiring board of claim 1, wherein said epoxy (a) and epoxy (b) are contained in total in an amount of 93% to 100% by weight, based on the total weight of the epoxy resin.

12. (currently amended): The prepreg for a printed wiring board of claim 1, wherein said epoxy (a) is contained in an amount of ~~90%~~ 91.8% to 96% ~~97%~~ by weight, based on the total weight of the epoxy resin.

13. (new): The prepreg for a printed wiring board of claim 1, wherein the epoxy (a) has an epoxy equivalent of 427 g/eq to 470 g/eq.

14. (new) The prepeg for a printed wiring board of claim 1, wherein said epoxy (a) is contained in an amount of 91.8 % by weight based on the total weight of the epoxy resin."

15. (new) The prepeg for a printed wiring board of claim 1, wherein said epoxy (a) is contained in an amount of 96 % by weight based on the total weight of the epoxy resin."

16. (new) The prepeg for a printed wiring board of claim 1, wherein said epoxy (a) is contained in an amount of 79 % by weight based on the total weight of the epoxy resin."

17. (new) The prepeg for a printed wiring board of claim 1, wherein said epoxy (a) is contained in an amount of 79 % to 96 % by weight based on the total weight of the epoxy resin."